

The Institute for Interconnecting and Packaging Electronic Circuits

## IPC-9501

PWB Assembly Process Simulation for Evaluation of Electronic Components (Preconditioning IC Components)



Original Publication July 1995

> 2215 Sanders Road Northbrook, Illinois 60062-6135

Tel 847 509.9700 Fax 847 509.9798 URL: http://www.ipc.org

## Notice

IPC Standards and Publications are designed to serve the public interest through eliminating misunderstandings between manufacturers and purchasers, facilitating interchangeability and improvement of products, and assisting the purchaser in selecting and obtaining with minimum delay the proper product for his particular need. Existence of such Standards and Publications shall not in any respect preclude any member or nonmember of IPC from manufacturing or selling products not conforming to such Standards and Publication, nor shall the existence of such Standards and Publications preclude their voluntary use by those other than IPC members, whether the standard is to be used either domestically or internationally.

Recommended Standards and Publications are adopted by IPC without regard to whether their adoption may involve patents on articles, materials, or processes. By such action, IPC does not assume any liability to any patent owner, nor do they assume any obligation whatever to parties adopting the Recommended Standard or Publication. Users are also wholly responsible for protecting themselves against all claims of liabilities for patent infringement.

The material in this standard was developed by the Component & Process Compatibility Task Group (5-21d) of the Assembly & Joining Processes Committee (5-20) of the Institute for Interconnecting and Packaging Electronic Circuits.



The Institute for Interconnecting

and Packaging

ELECTRONIC CIRCUITS

IPC-9501

## PWB Assembly Process Simulation for Evaluation of Electronic Components (Preconditioning IC Components)

Developed by the Component & Process Compatibility Task Group (5-21d) of the Assembly & Joining Processes Committee (5-20) of the Institute for Interconnecting and Packaging Electronic Circuits

Users of this standard are encouraged to participate in the development of future revisions.

Contact:

IPC 2215 Sanders Road Northbrook, Illinois 60062-6135 Tel 708 509.9700 Fax 708 509.9 798

Not for Resale